

Bill of materials

Item	Part	Qʻty	Value	Part name	Manufac turer	Description	Package Name	Standard dimension mm (inch)	Comments
1	IC1	1	-	TCKE805	TOSHIBA	eFuse IC	WSON10B	3.0×3.0×0.7	All NA/NL can be used
2	Q1	1	-	SSM6K513NU	TOSHIBA	Nch MOSFET	UDFN6B	2.0×2.0×0.75	
3	C1, C4	2	1 μF			Ceramic 25 V, ±10 %		1.6×0.8 (0603)	
4	C2	1	120 pF			Ceramic 50 V, ±5 %		1.0×0.5 (0402)	
5	R1, R2	2						1.0×0.5 (0402)	Not mounted
6	R3	1	36 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
7	CN1	1	-	022284063	Molex	Test pin 6 pins		Pitch of 2.54 mm	
8	CN2	1	-	022284043	Molex	Test pin 4 pins		Pitch of 2.54 mm	



Term of service

This Agreement sets forth the terms and conditions for the use of documents and data (hereinafter referred to as "Reference Design") that will be useful for designing devices with our semiconductor products between customers and Toshiba Devices & Storage Co., Ltd. (hereinafter referred to as "We"). You must comply with this Agreement. You are deemed to have agreed to this Agreement by downloading this Reference Design. This Agreement may be modified. We may terminate this Agreement at any time, for any reason whatsoever. If this Agreement is terminated, Customer must destroy this Reference Design. If you violate this Agreement, you must destroy the Reference Design and submit to us a document certifying that you have destroyed it.

Article 1 Prohibition

Customers' prohibitions are as follows.

- 1. This reference design is intended to be used as reference data for device design. Do not use the product for other purposes, such as reliability verification.
 - 2. Do not sell, transfer, or lease this reference design.
- 3. This reference design cannot be used to evaluate the environment against high and low temperatures, high humidity, strong electromagnetic fields, etc.
- 4. Do not use this reference design in products that are prohibited from being manufactured, used, or sold by laws, regulations, and orders in Japan and overseas.

Article 2 Guarantee Restrictions, etc.

- 1. This reference design may be changed without prior notice due to technological progress.
- 2. This reference design is data for reference. We make no guarantee as to the accuracy or completeness of data and information.
- 3. The semiconductor device may malfunction or malfunction. When designing equipment with reference to this reference design, the customer's responsibility is to carry out the safety design necessary for the customer's hardware, software, and system in order to prevent the life, body, and property from being infringed by malfunction or malfunction. Confirm and follow the latest information on the semiconductor devices used (semiconductor reliability handbook, specifications, data sheet, application notebook, etc.).
- 4. When designing a device with reference to this reference design, fully evaluate the entire system and judge whether it is applicable or not at the customer's responsibility. We are not liable for the applicability.
- 5. This Reference Design does not guarantee or license our and any third party intellectual property rights or other rights in the use thereof.
- 6. We have no express or implied warranty (including, but not limited to, warranty of functional operation, warranty of merchantability, guarantee of conformity to a specific purpose, guarantee of accuracy of information, non-infringing warranty of rights of third parties), nor are we liable for any damages (including, but not limited to, indirect damages, consequential damages, special damages, incidental damages, lost profits, loss of opportunity, loss of absence from work, loss of data, etc.) in respect of this Reference Design.

Article 3 Export control

You must not use this reference design for purposes such as the development of weapons of mass destruction, military applications, or other military applications. In addition, customers must comply with applicable export-related laws and regulations, such as the Foreign Exchange and Foreign Trade Law and the U.S. Export Control Regulations.

Article 4 Governing Law

The applicable law of this Agreement shall be the Japanese law.

2019-11-01